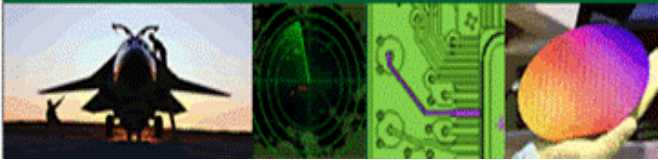




Bringing Together The Entire Microelectronics Supply Chain!



Industry
Systems & Applications
Design
Materials & Process

IMAPS San Diego Chapter

Tuesday, February 22 at 12:00

Please join us for a technical presentation, industry lunch and facility tour.

Impact of Mechanical Simulation Methodology on Electronic Package Reliability
Assessment with Applications to 3D TSS Technology

Presentation:

Recent rapid growth of various portable electronic devices like Smartphone and smart book with increasing demand for more functionality in tighter space challenges the limit of mechanical reliability. To reduce the product development cost and time-to-market, mechanical simulation has been extensively employed in semiconductor industry for the purpose of design optimization and reliability assessment. The importance of having the correct simulation methodology can't be overemphasized considering the extent of its utilization throughout the product development cycle. Simulated warpage, as well as reliability assessment regarding different failure mechanisms using these three modeling methodologies are discussed.

Dr. Andy Bao is a Staff Engineer specializing in process and packaging technology development at Qualcomm, Inc. since 2009. He has worked extensively on BEOL process optimization, 45nm/32nm/28nm ELK cracking assessment, package thermal analysis, wafer-level packaging, and through-silicon stacking technologies. Before joining Qualcomm, Dr. Bao was a Senior Engineer at Intel. He graduated with Ph.D from Department of Mechanical & Aerospace Engineering at Cornell University in August 2004.

Logistics:

Tuesday, February 22. 12:00 Lunch and Presentation. Facility tour to follow.

Quik-Pak

10987 Via Fronterria

San Diego, CA 92127

[Click here for Map and Directions](#)

Cost: \$20.00 for RSVPed IMAPS and ACerS Members. \$25.00

Others. Complimentary for students with ID.

Please RSVP by Monday, February 21 at 2:00* SEATING IS LIMITED!

To register, please contact Dave Virissimo of Semiconductor Packaging Materials at dvirissimo@sempck.com or 619-464-5430